

ABSTRACT

5 Provided is a resin composition which enables the
formation of a roughened surface having a low roughness
degree on the surface of an insulation layer in a printed
wiring board material when used on the insulation layer
regardless of the roughening conditions employed and also
enables the formation of a conductive layer having
excellent adhesion properties, heat resistance, heat
10 resistance under absorption of moisture, thermal
expansion properties and chemical resistance on the
roughened surface. A resin composition comprising (A) an
inorganic filler that is soluble in an acid, (B) a cyanic
acid ester compound and (C) an epoxy resin.

NO FIGURE